

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00283	1.54	0.04774
	Doped silicon	Silicon (Si)	7440-21-3	0.18114	98.46	3.05226
		Subtotal		0.18397	100	3.1
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.00499	5.0	0.08407
	Silver alloy	Silver (Ag)	7440-22-4	0.0015	1.5	0.02522
	Lead alloy	Lead (Pb)	7439-92-1	0.0933	93.5	1.57208
		Subtotal		0.09979	100	1.68137
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.1187	100.0	2.00024
		Subtotal		0.1187	100	2.00024
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0654	0.1	1.102
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01962	0.03	0.3306
	Copper alloy	Copper (Cu)	7440-50-8	65.31357	99.87	1100.5674
		Subtotal		65.39859	100	1102
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.13471	100.0	2.27
		Subtotal		0.13471	100	2.27
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.53289	4.5	25.83
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.40642	10.0	57.4
	Filler	Silica fused	60676-86-0	25.54818	75.0	430.5
	Metal hydroxide	Metal hydroxide		3.40642	10.0	57.4
	Carbon Black	Carbon black	1333-86-4	0.17032	0.5	2.87
		Subtotal		34.06423	100	574
		Total		99.99999	100	1685.05161

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